

ABSTRACT OF THE DISCLOSURE

This invention relates to a sheet feeding type wafer polishing machine which processes both surfaces of wafer and outermost periphery of wafer (edge part) in series, having two platens stuck with a polishing pad or a grinding stone and holding a wafer therebetween. The surface of said wafer is processed by rotating at least one of said two platens and wafer, wherein the diameter of said platens are bigger than the radius of said wafer and smaller than the diameter of said wafer, and said wafer is supported by at least three guide rollers which contact to the outermost periphery of said wafer. Further, the present invention provides an edge polishing and a surface polishing method by said wafer processing machine.

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